



40GBASE-LR/LW SMF 1310nm 10km QSFP+ Optical Transceiver with Duplex MPO Connector

40GSLWSFPC



DESCRIPTION

The 40GSLWSFPC QSFP+ PSM4 transceiver is a new high-speed module with a MPO connector. This interconnecting module offers 4 channels and maximum bandwidth of 40Gbps. The module consists of 4x10Gbps 1310nm DFB LDs transmitter and 4x10G PINs receiver.

FEATURES

- Supports 4x10GBASE-LR
- Power dissipation < 3.5W with single 3.3V power supply
- Full Digital Diagnostics Monitor Interface
- Up to 10km transmission on SMF
- RoHS-6 Compliant (lead-free)
- MPO12 receptacle
- Temperature: 0°C to 70°C
- Up to 10km over single mode fiber

APPLICATIONS

- 4x10GBASE-LR/LW
- Data Center Interconnect

ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL	MIN	MAX	UNIT
Storage Temperature	T _s	-40	85	°C
Supply Voltage	V _{CC}	-0.5	3.6	V
Relative Humidity	RH	5	85	%

RECOMMENDED OPERATING CONDITIONS

PARAMETER	SYMBOL	MIN	TYP.	MAX	UNIT
Case Temperature	T _c	0		70	°C
Power Supply Voltage	V _{CC}	3.14	3.3	3.47	V
Power Dissipation				2.5	W

DIAGNOSTICS

PARAMETER	RANGE	ACCURACY	UNIT	CALIBRATION
Temperature	-5 to 75	±3	°C	Internal
Voltage	3.0 to 3.6	±0.1	V	
Bias Current	0 to 100	±10%	mA	
TX Power	-5 to +6	±3 dB	dBm	
RX Power	-24 to 0	±3 dB	dBm	

TRANSMITTER OPTICAL CHARACTERISTICS

PARAMETER	SYMBOL	MIN	TYP.	MAX	UNIT
Average Output Power, per lane	P _O	-8.2		+0.5	dBm
Optical Modulation Amplitude, per lane	P _{OMA}	-5.2		+2	dBm
Extinction Ratio	ER	3.5			dB
Center Wavelength	λ _c	1260		1360	nm
Side Mode Suppression	SMSR	30			dB
Relative Intensity Noise	RIN200MA			-128	dB/Hz
Optical Return Loss	ORL			-12	dB
Transmitter and Dispersion Penalty	TDP			2.3	dB
Differential Input Swing		200		800	mV
Disable Output Power	P _{o_off}			-30	dBm
Output Eye Mask		Compliant with IEEE 802.3ba			

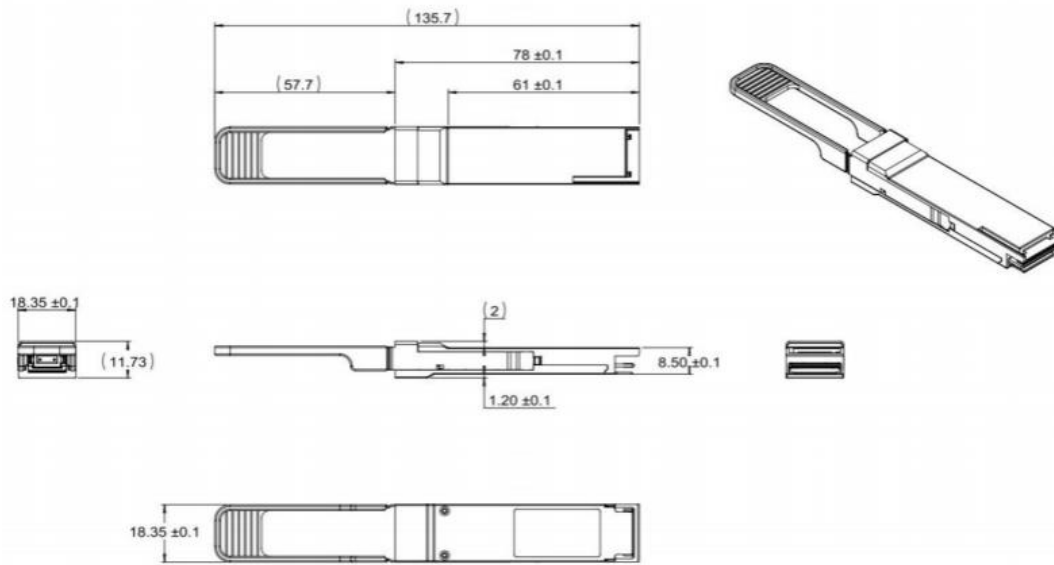
RECEIVER OPTICAL CHARACTERISTICS

PARAMETER	SYMBOL	MIN	TYP.	MAX	UNIT
Damage Threshold, per lane	P _{th}	3.3			dBm
Average Power at Receiver Input, per lane	P _{IN}	-14.2		0.5	dBm
Receiver Power (OMA), per lane				0.5	dBm
Receiver Sensitivity (OMA), per lane	R _{sens}			-12.6	dBm
Differential Output Swing		400		850	mV
LOS Assert	LOS _A	-30			dBm
LOS De-Assert	LOS _D			-15	dBm
Hysteresis	Hys	0.5		6	dB

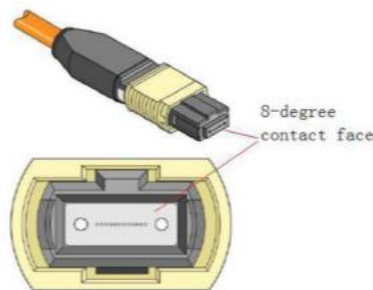
ELECTRICAL CHARACTERISTICS

PARAMETER	SYMBOL	MIN	TYP.	MAX	UNIT	NOTE
Data Rate, per lane			10.3125		Gbps	
LP Mode/Reset/Modsell	V _{IL}	0		0.8	V	
LP Mode/Reset/Modsell	V _{IH}	2		V _{CC} +0.3	V	
ModPrsL/IntL	V _{OL}	0		0.4	V	
ModPrsL/IntL	V _{OH}	2		V _{CC} +0.3	V	

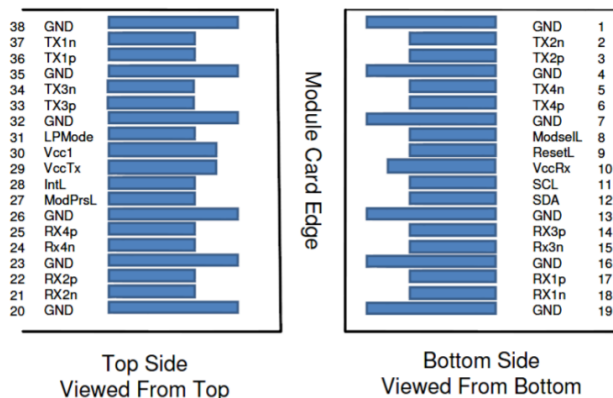
DIMENSIONS (unit: mm)



[Attention] To minimize MPO connection induced reflections, an MPO receptacle with 8-degree angled end-face is utilized for this product. A male MPO connector with 8-degree end-face should be used with this product as illustrated below.



PAD ASSIGNMENT AND DESCRIPTION

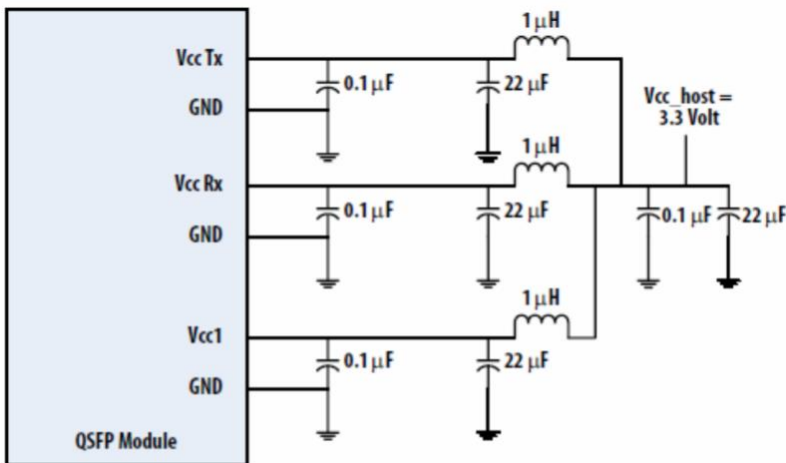


"PIN	LOGIC	SYMBOL	DESCRIPTION	PLUG SEQUENCE	NOTE
1		GND	Ground	1	Note 1
2	CML-I	Tx2n	Transmitter Inverted Data Input	3	
3	CML-I	Tx2p	Transmitter Non-Inverted Data Input	3	
4		GND	Ground	1	Note 1
5	CML-I	Tx4n	Transmitter Inverted Data Input	3	
6	CML-I	Tx4p	Transmitter Non-Inverted Data Input	3	
7		GND	Ground	1	Note 1
8	LVTTL-I	ModSelL	Module Select	3	
9	LVTTL-I	ResetL	Module Reset	3	
10		Vcc Rx	+3.3V Power Supply Receiver	2	Note 2
11	LVCMOS-I/O	SCL	2-wire serial interface clock	3	
12	LVCMOS-I/O	SDA	2-wire serial interface data	3	
13		GND	Ground	1	Note 2
14	CML-O	Rx3p	Receiver Non- Inverted Data Output	3	
15	CML-O	Rx3n	Receiver Inverted Data Output	3	
16		GND	Ground	1	Note 1
17	CML-O	Rx1p	Receiver Non- Inverted Data Output	3	
18	CML-O	Rx1n	Receiver Inverted Data Output	3	
19		GND	Ground	1	Note 1
20		GND	Ground	1	Note 1
21	CML-O	Rx2n	Receiver Inverted Data Output	3	
22	CML-O	Rx2P	Receiver Non- Inverted Data Output	3	
23		GND	Ground	1	Note 1
24	CML-O	Rx4n	Receiver Inverted Data Output	3	
25	CML-O	Rx4p	Receiver Non- Inverted Data Output	3	
26		GND	Ground	1	Note 1
27	LVTTL-O	ModPrsL	Module Present	3	
28	LVTTL-O	IntL	Interrupt	3	
29	LVCMOS-I/O	Vcc Tx	+3.3V Power Supply transmitter	2	Note 2
30		Vcc1	+3.3V Power Supply	2	Note 2
31	LVTTL-I	LPMODE	Low Power Mode	3	
32		GND	Ground	1	Note 1
33	CML-I	Tx3p	Transmitter Non- Inverted Data Input	3	
34	CML-I	Tx3n	Transmitter Inverted Data Input	3	
35		GND	Ground	1	Note 1
36	CML-I	Tx1p	Transmitter Non- Inverted Data Input	3	
37	CML-I	Tx1n	Transmitter Inverted Data Input	3	
38		GND	Ground	1	Note 1

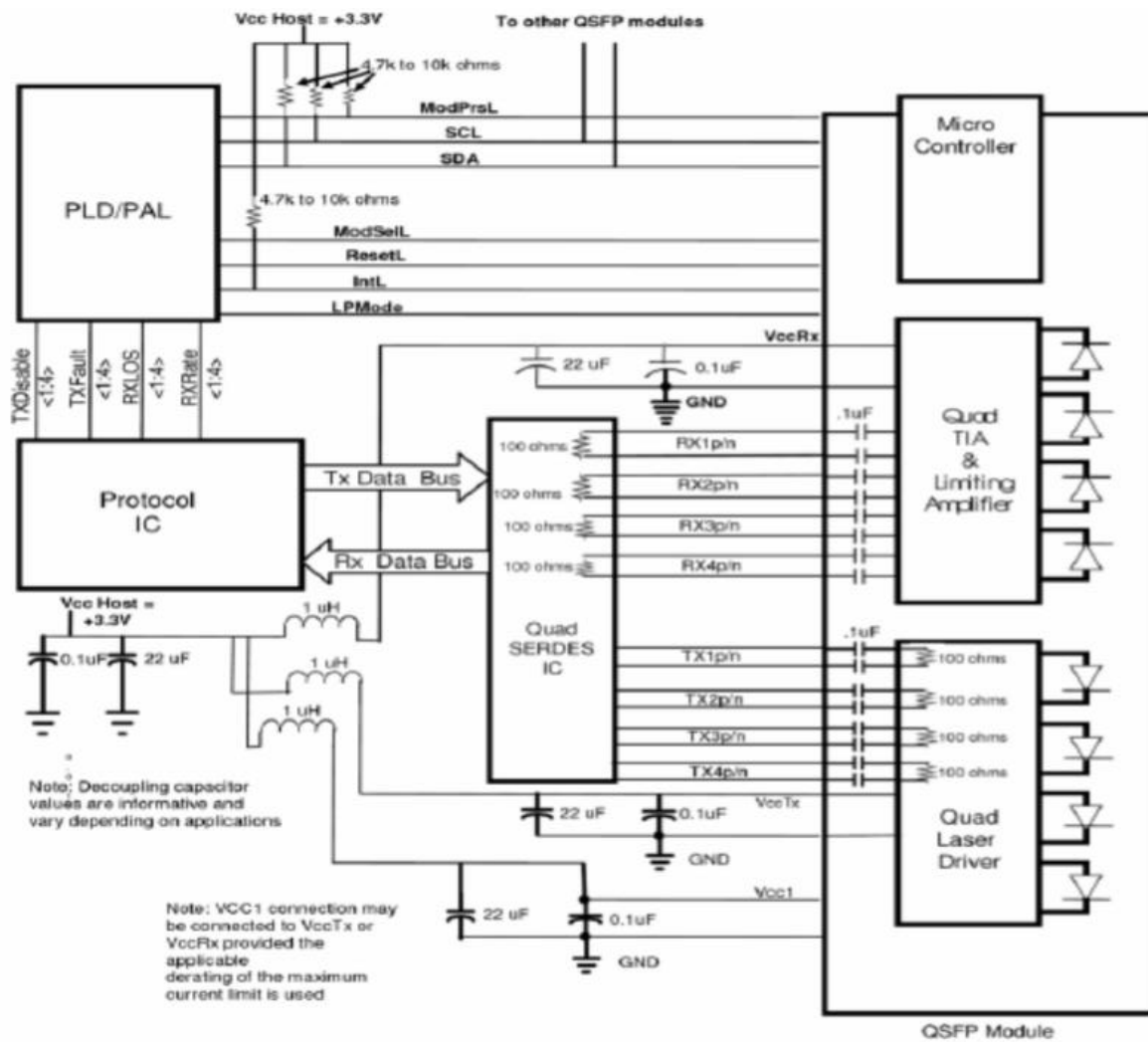
Note 1: GND is the symbol for signal and supply (power) common for the QSFP module. All are common within the QSFP+ module and all module voltages are referenced to this potential unless otherwise noted. Connect these directly to the host board signal-common ground plane.

Note 2: Vcc Rx, Vcc1 and Vcc Tx are the receiver and transmitter power supplies and shall be applied concurrently. Requirements defined for the host side of the Host Edge Card Connector are listed in Table. Recommended host board power supply filtering is shown in Host board power supply circuit. Vcc Rx Vcc1 and Vcc Tx may be internally connected within the QSFP+ module in any combination. The connector pins are each rated for a maximum current of 500 mA.

HOST BOARD POWER SUPPLY CIRCUIT

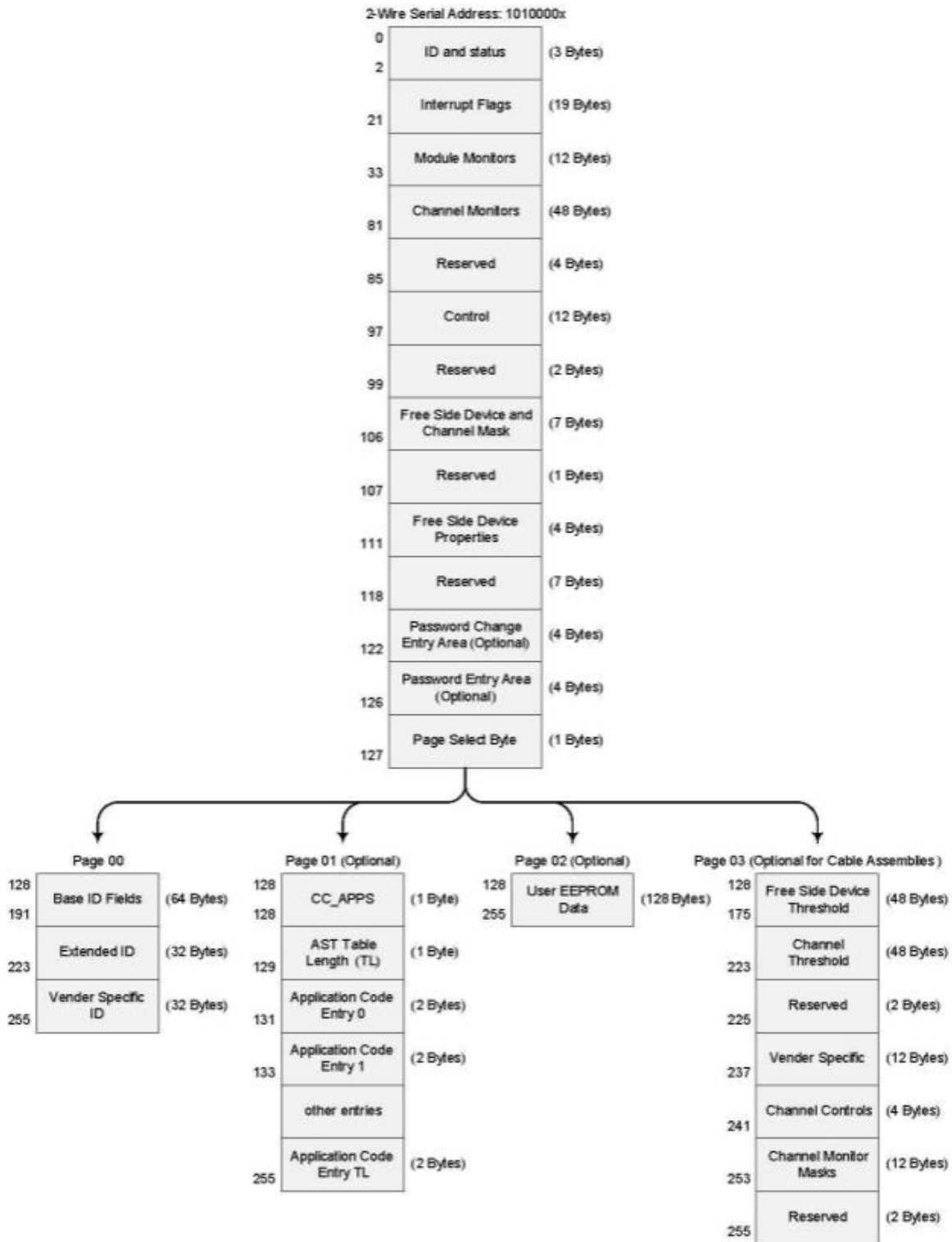


RECOMMENDED INTERFACE CIRCUIT



MEMORY MAP

The memory map is structured as a single address and multiple page approaches, according to the QSFP+ SFF-8436 MSA specification as shown in the below. For more detailed description of this memory map or lower pages, please see our Memory Map document with flexible customization settings.



ADDITIONAL NOTES

- Avoid eye or skin exposure to laser radiations.
- The device is sensitive to electro-static discharge (ESD). The device should be handled with ESD proof tools. To assemble the device on PCB, proper grounding is required to prevent ESD.
- Specifications are subject to change without notice.



Lasermate Group, Inc.
19608 Camino De Rosa
Walnut, CA 91789 USA
Tel: (909)718-0999
Fax: (909)718-0998
sales@lasermate.com
www.lasermate.com